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TITLE: 360 I/O, TEPBGA, 23 X 23 PKG, 1 MM PITCH (OMPAC)	DOCUMENT NO: 98ARE10605D	REV: B
	STANDARD: JEDEC MS-034 AAJ-1	
	SOT1708-1	01 FEB 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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